

## AMENDMENTS TO THE SPECIFICATION

**Please amend paragraph [0003] on page 2, as follows:**

[0003] In the above example, a region with a base plate in which the adhesive holding layer is provided for adhering an FPC thereto is referred to as an "adhesive holding region." Thus, the adhesive holding layer itself is provided in the adhesive holding region of the base plate. In the above example, a region of the base plate in which the adhesive holding layer is provided for adhering an FPC thereto is referred to as an "adhesive holding region", as opposed to the adhesive holding layer itself which is provided in the adhesive holding region. When electronic components must be mounted on an FPC which is adhered to a base plate, it is imperative that the shape of the adhesive holding layer (~~adhesive holding region~~) and the adhesive holding layer's adhesion ability to the FPC be optimally designed. In the case where electronic components are mounted on an FPC by using solder paste, a series of steps are performed to effectuate the mounting, including: screen printing of solder paste onto the FPC; installation of the electronic components; and a reflow (heating and cooling).

**Please amend paragraph [0031] on page 16, as follows:**

**[0031]** As described above, the pallet 1a holds the entire FPC 9 with its adhesion ability so as to prevent the FPC 9 from peeling off the pallet 1a during the mounting of electronic components. Moreover, the first adhesive holding region 21, which holds the peripheral portion of the FPC 9 with a relatively low tackiness and the second adhesive holding region 22, which holds the central portion of the FPC 9 with a higher tackiness than that of the first adhesive holding region 21, facilitate the screen printing process. Furthermore, the use of blown air makes it possible to peel the FPC 9, which has electronic components mounted thereon, safely off the pallet 1a. Thus, the use of the pallet 1a facilitates the handling of the FPC 9 in the entire operation line related to mounting. As becomes clear from the above, the tackiness between the first adhesive holding region and the planar base late 11, which serves as the main body, as well as the tackiness between the second adhesive holding region and the main body, are larger than the tackiness of both the first and second adhesive holding regions 21 and 22. In other words, the

adhesive holding layer 12 is formed on the main body so that the adhesive holding layer 12 remains on the main body upon separation of the FPC 9 from the first adhesive holding region 21 and the second adhesive holding region 22.

**Please amend paragraph [0067] on page 31, as follows:**

[0067]       The pallets 1a to 1f described in the above embodiments utilize an adhesive material which is provided on a base plate 11. Alternatively, for example, the substrate holder according to the present invention may be produced by processing a single adhesive member. In this case, ~~there will be no adhesive holding layer, and~~ the main portion of the substrate holder will be composed of the same material that composes the holding surface.